

# MTD BTL **Thermal** Test Setup

2024 CLHCP QingDao

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on behalf of

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# Outline



- General Introduction
- SM QA/QC Thermal Test
- DM QA/QC Thermal Test
- BTL Tray QA/QC setup
- Summary



# General Introduction

# Assembly of MTD BTL

## ➤ Sensor Module Assembly

- 1 Lyso + 2 Sipm
- SM QA/QC



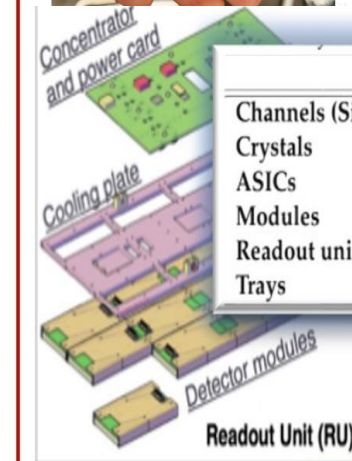
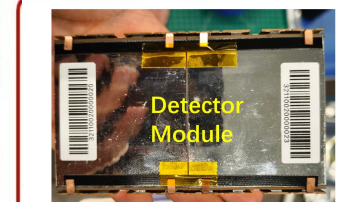
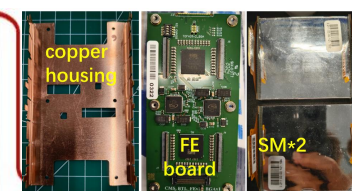
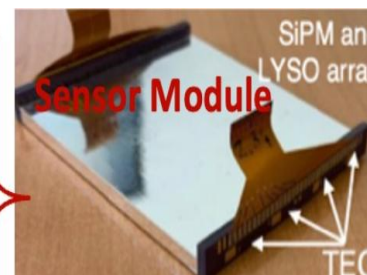
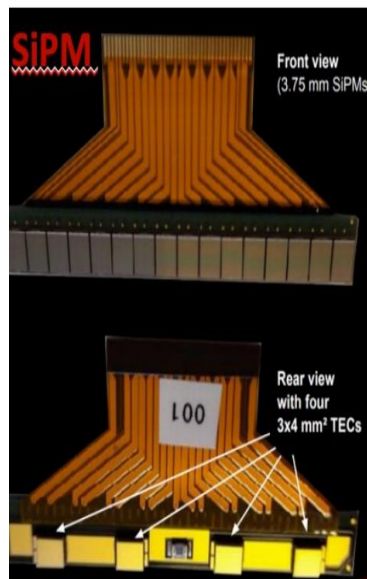
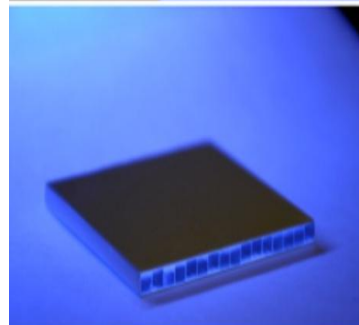
## ➤ Detector Module Assembly

- 1 Copper Housing
- 2 SM 1 FE board
- DM QA/QC



## ➤ BTL Tray Assembly

- ~72 DM 6 Readout Units 12DMs/RU
- BTL Tray QA/QC



	Module	RU	Tray	Total
Channels (SiPMs)	32	768	4608	331776
Crystals	16	384	2304	165888
ASICs	1	24	144	10368
Modules	-	24	144	10368
Readout units (RU)	-	-	6	432
Trays	-	-	-	72





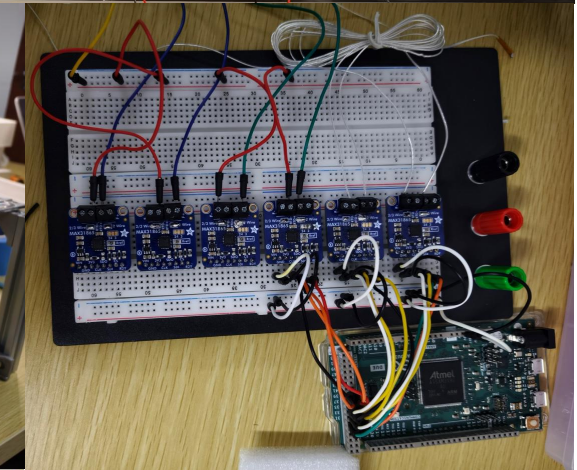
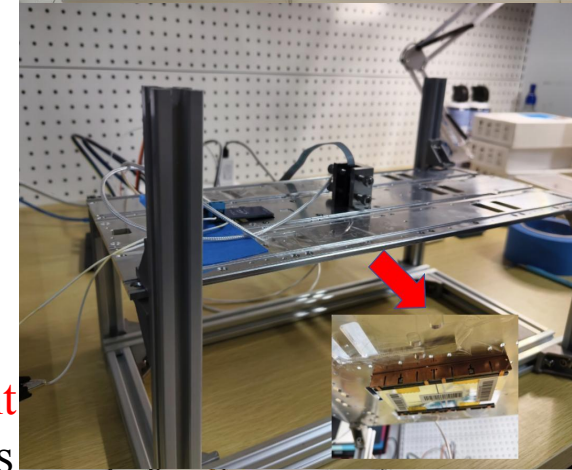
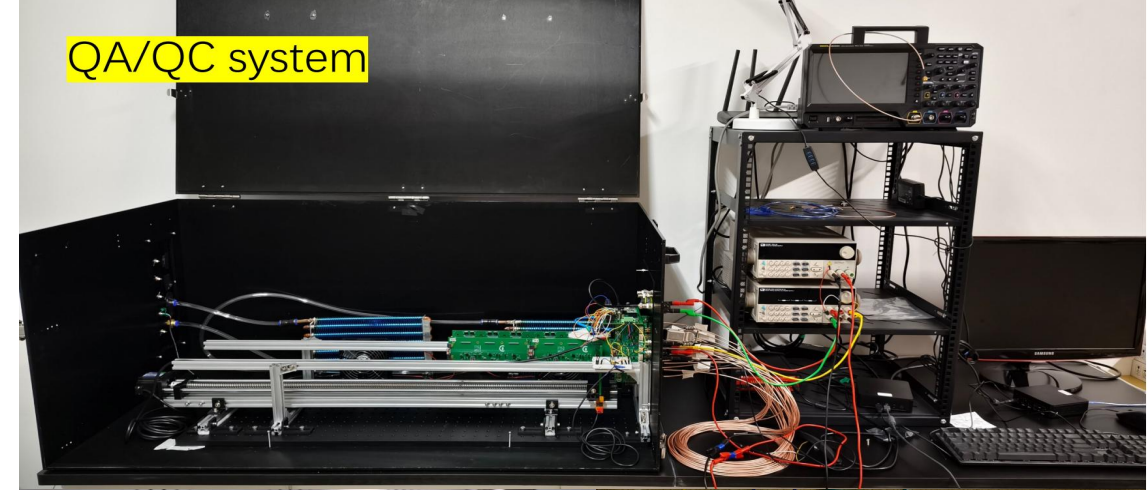
# QA/QC & Thermal Test

## ➤ QA/QC

- **SM QA/QC**: measure the **light yield** of each channel of sensor module to show the assembly quality
- **DM QA/QC**: mainly involves **thermal coupling** testing
- **BTL Tray QA/QC**: including **bias power** supply, **temperature** testing and **DAQ**, etc., while optimizing QA/QC

## ➤ Why Thermal Test

- SM QA/QC Thermal test covers **temperature control and measurement** in QA/QC experiment condition, standardizing SM QA/QC conditions across four BACs for consistency
- **Ensures good contact between** the **TECs on the SiPM** and copper
- **SiPM** and DAQ system have **strict temperature requirements**, making temperature control and real-time monitoring essential in QA/QC



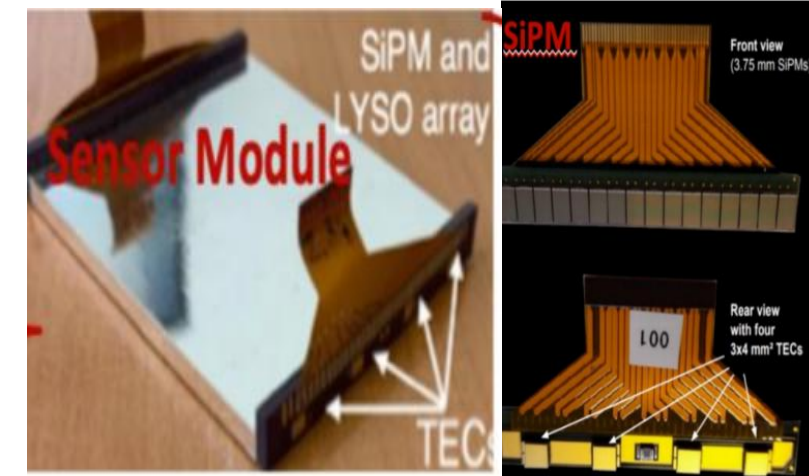
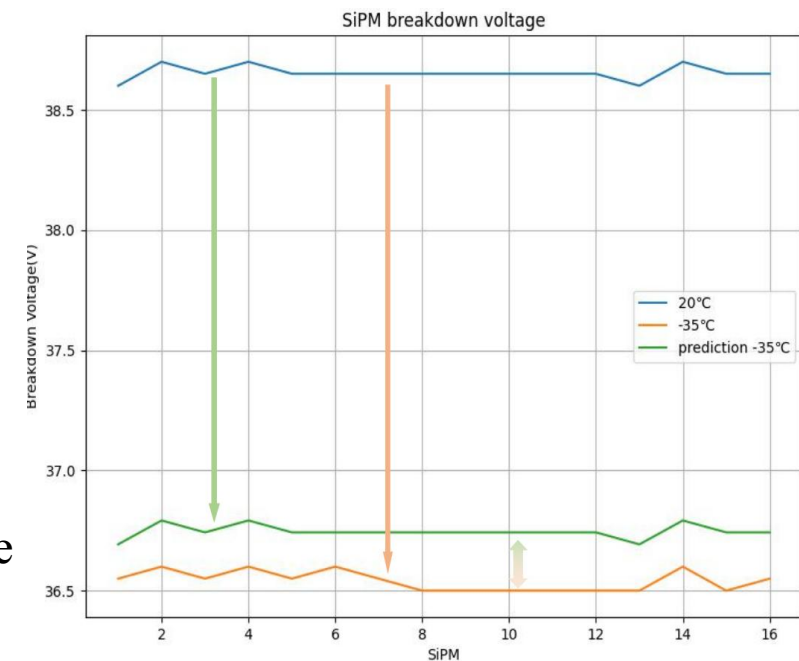


# SM QA/QC Thermal Test

# Why SM QA/QC Thermal Test



- Different SiPMs has different **breakdown voltage,  $V_{br}$**  , The temperature has large impact on the  $V_{br}$
- Compared to the actual temperature of CMS ( $\sim -35^{\circ}\text{C}$ ), the lab temperature ( $\sim 20^{\circ}\text{C}$ ) causes a significant difference in the  $V_{br}$  of the same SiPM
- Since the SM QA/QC voltage is proportional to  $V_{br}$ , during batch testing temperature inconsistencies in SiPMs will cause significant deviations in the final **light yield**.
- Therefore, all BACs standardize the SM QA/QC temperature to  $23^{\circ}\text{C}$  for **consistent metrics**



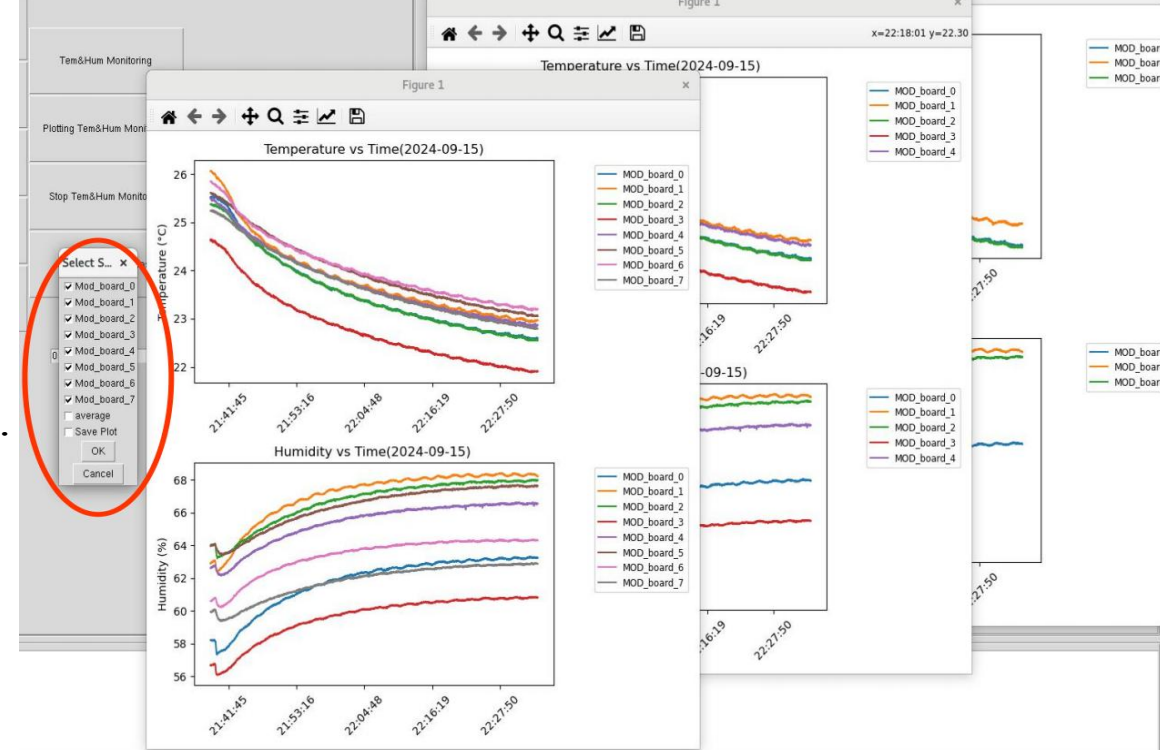
$$V_{T_A} = V_{T_B} - 34mV/^{\circ}C \cdot (T_B - T_A)$$





# Temperature monitoring GUI panel

- Use the "Tem&Hum monitoring" button to perform **temperature monitoring** and **save the data** at regular intervals
- During the testing process, the **temperature** and humidity data of **each module position** will be displayed in real-time on the GUI panel.
- The average data will also be displayed on the GUI panel in real-time
- You can choose any Module's data (including average) drawn on a canvas at any time

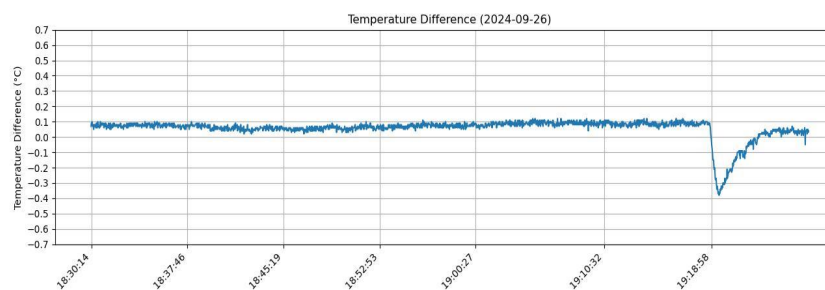
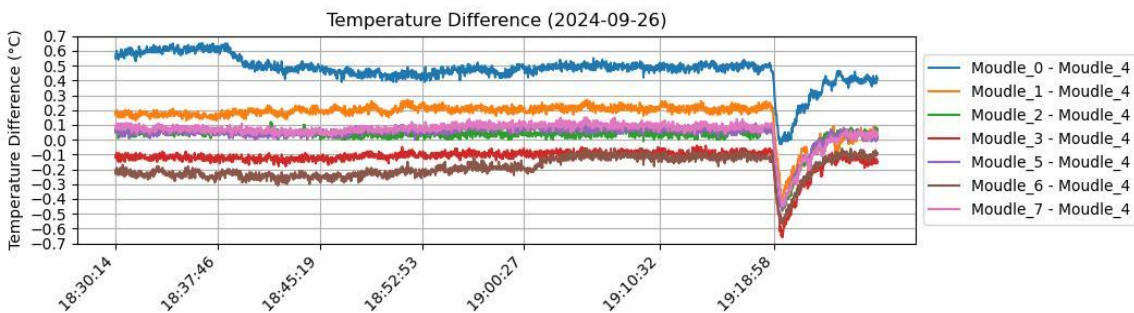
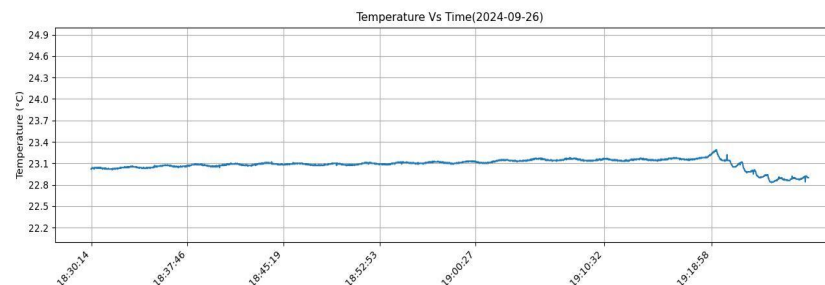
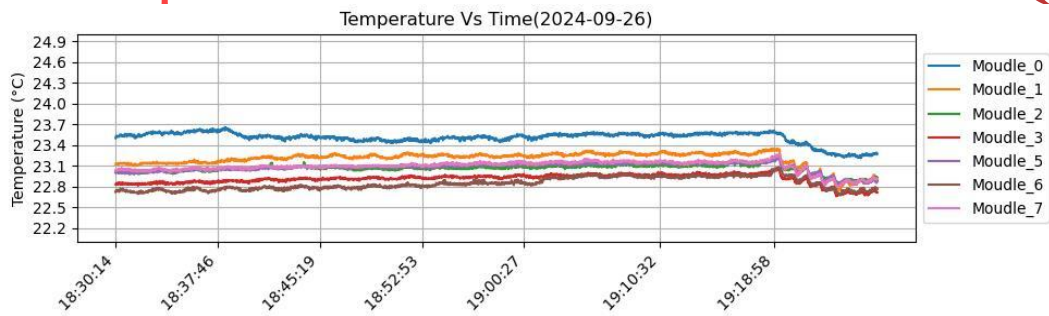


The screenshot shows the "BTL QA/QC GUI" interface. On the left is a control panel with buttons: "Take Data", "Tem&Hum Monitoring" (highlighted with a red box), "Stop", "Plotting Tem&Hum Monitoring", "Stop Tem&Hum Monitoring", "Reanalyze Data", "Stepper Home", "Get Vcd from Database", and "Stepper To Module". On the right is a settings panel with fields for "Assembly Center", "Number of Boards", "OV (V)", "Trigger Threshold (V)", "IP Address", "Data path", "Extra label", "Number of SPE Events", "Number of Source Events", and "Enable stepper motor". Below the settings is a table of barcode and voltage data. At the bottom is a "Temperatures" table with real-time data for eight modules and an average.

Temperatures			
Tem(°C): 22.94	Tem(°C): 23.21	Tem(°C): 22.01	Tem(°C): 23.04
Hum(%): 62.79	Hum(%): 67.54	Hum(%): 60.71	Hum(%): 68.29
MOD_board_7	MOD_board_5	MOD_board_3	MOD_board_1
MOD_board_6	MOD_board_4	MOD_board_2	MOD_board_0
Tem(°C): 23.31	Tem(°C): 22.99	Tem(°C): 22.69	Tem(°C): 22.70
Hum(%): 64.26	Hum(%): 66.48	Hum(%): 67.88	Hum(%): 63.11
<b>Average:</b>			
Timestamp: 2024-09-15 22:27:01			
Temperature (°C): 22.86			
Humidity (%): 65.13			



# Temperature detection in formal QA/QC testing

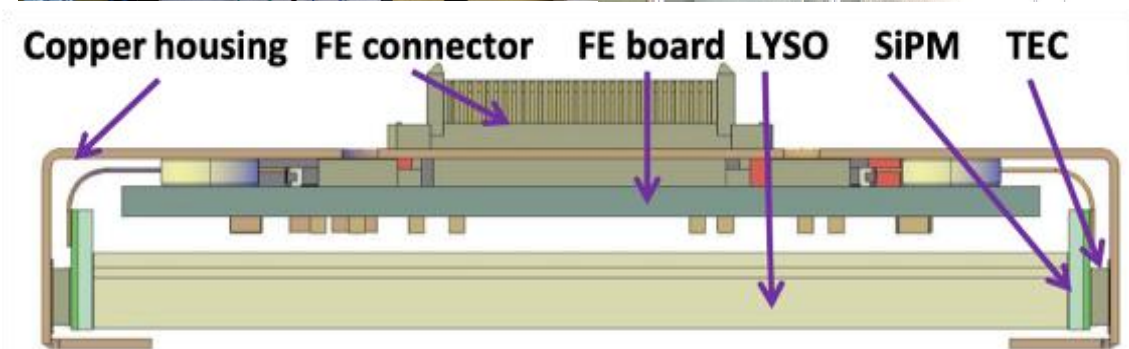
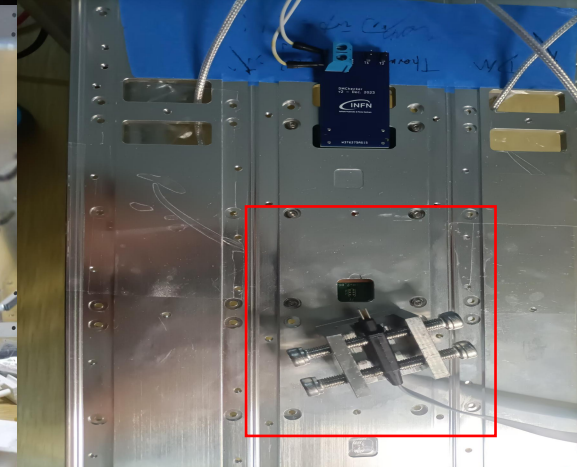
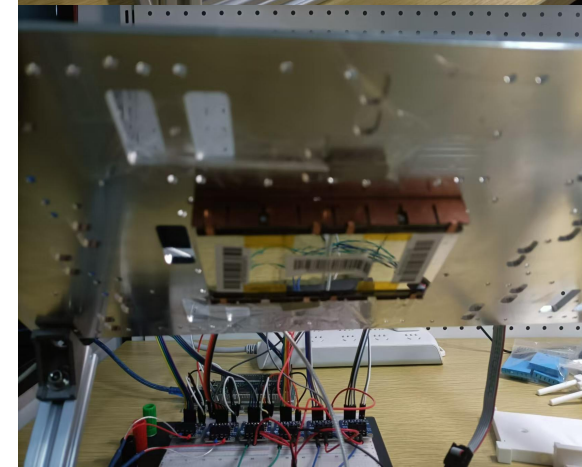
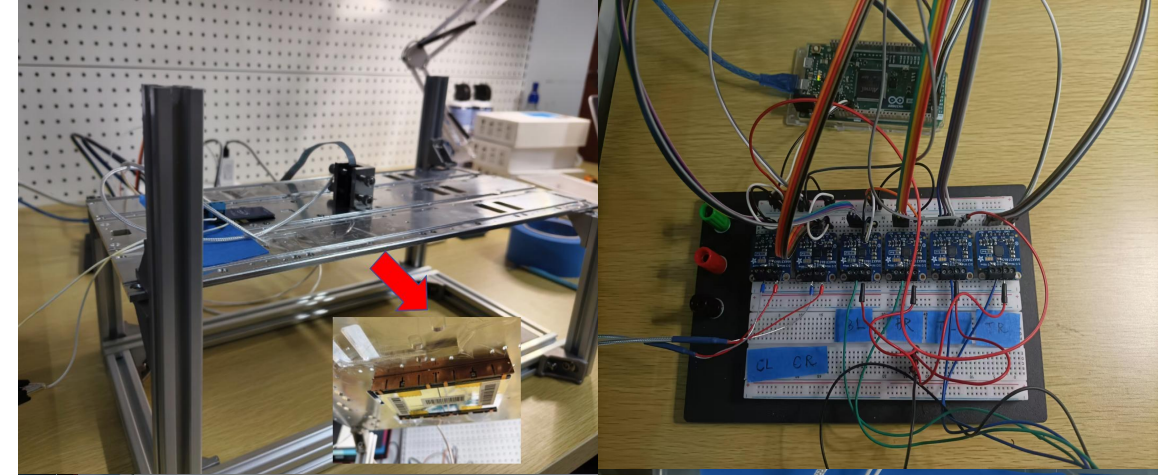


- Before SM QA/QC, the temperature data of Moudle\_4 sensor will calibrate the others, as it has been calibrated with a higher precision thermometer
- After correction, the temperature differences across 8 positions are minimal ( $\pm 0.1^{\circ}\text{C} \sim \pm 0.2^{\circ}\text{C}$ ), indicating **temperature uniformity** in the entire dark box
- Only the temperature near Moudle\_0 is relatively high (because it is close to control board, is affected by heat from it)
- The average temperature inside the box remained stable at  $\sim 23^{\circ}\text{C}$  during the QA/QC process, and the QA/QC test went smoothly

# DM Thermal Test

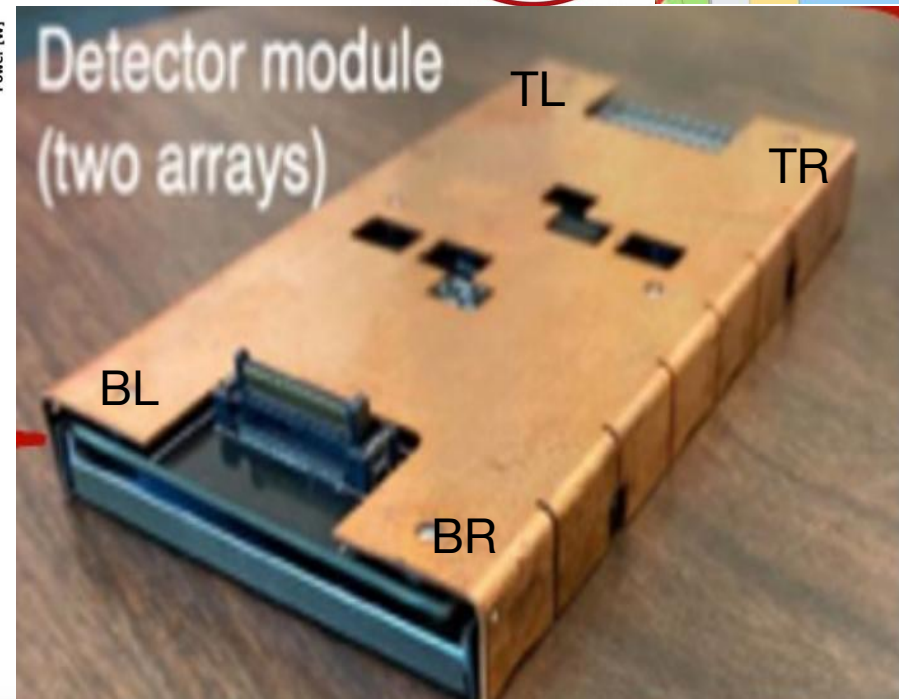
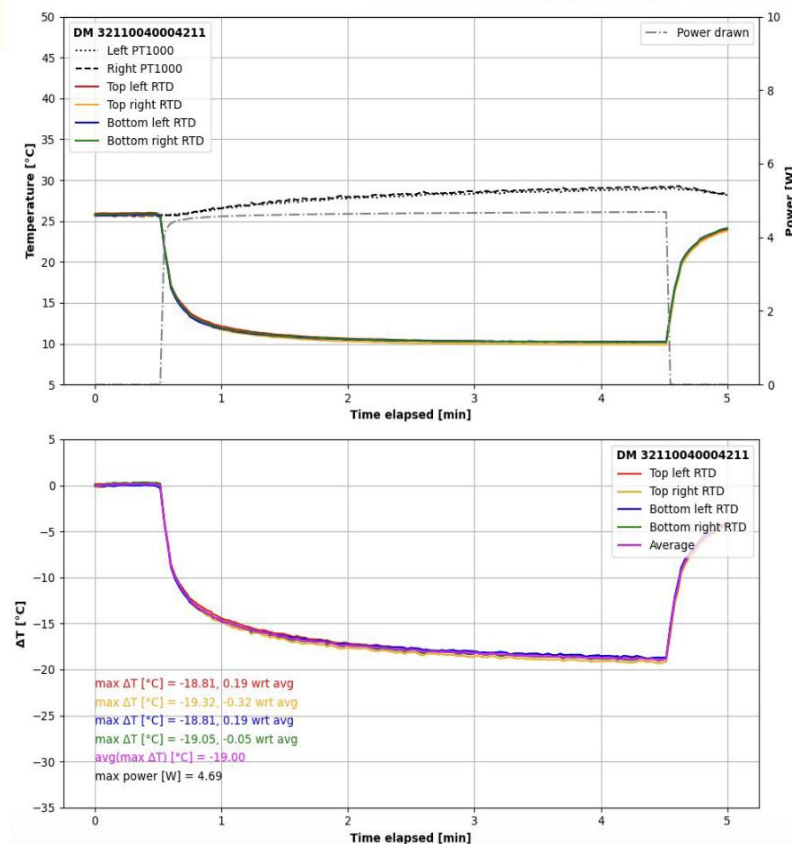
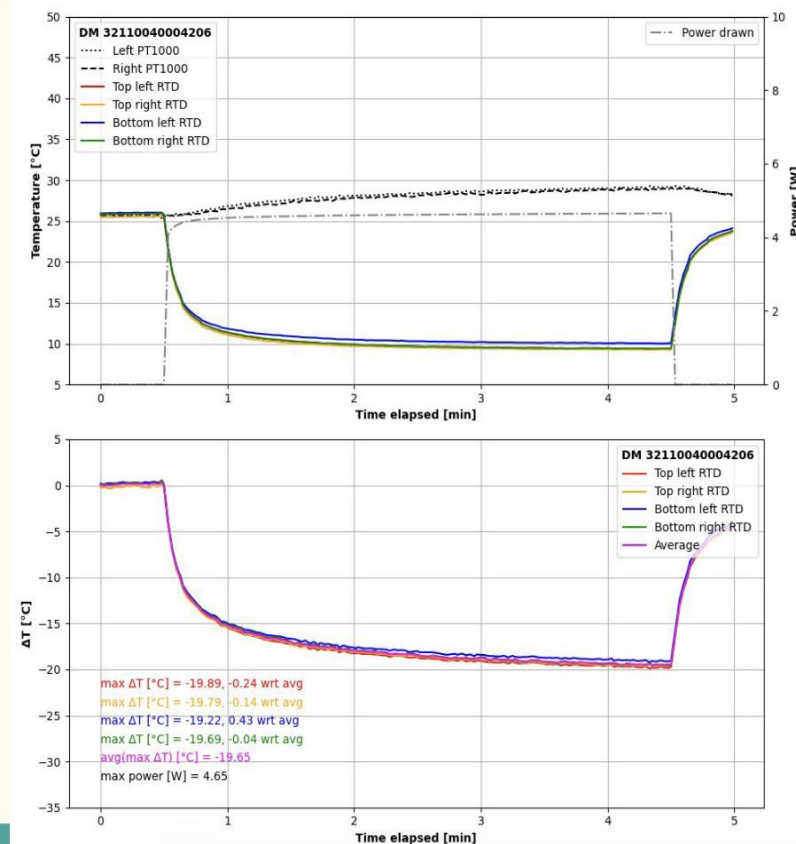
# Introduction of DM QA/QC Thermal Test

- Detector Module : Sensor module, FE front-end electronic board, and copper housing shell for **heat exchange**
- The temperature of the DM QA/QC system is measured using 6 MAX31865 modules and 2 Pt1000 sensors
- Two Pt1000s are connected to the **bottom** of the DM QA/QC cooling plate for measuring its temperature
- The remaining four MAX31865 modules are pinned through the cooling plate's top opening to the DM slots, measuring temperature at **four SiPMs(TL,TR,BL,BR)**.
- Injecting currents to 16 TECs of SiPMs from the DM and **measuring temperature** differences at four locations, along with the cooling plate temperature, **ensures good contact between the TECs on the SiPM and copper**, evaluating the DM's assembly quality and **thermal conductivity**.





# DM QA/QC Thermal Test Status



- Applying voltage to the TECs causes the SiPMs temperatures to decrease.
- As the temperature decreases, the **small temperature differences (RMS( $\Delta T$ )  $\sim 0.4^\circ\text{C}$ )** across the four positions indicate **good temperature uniformity** in the DM and a **well-assembled structure**
- The maximum temperature difference with the cooling plate, **max  $\Delta T$  (-19.65, -19.00)**, is within the **DM QA/QC standard range**, indicating that the assembly quality from SM to DM **meets the standard**.

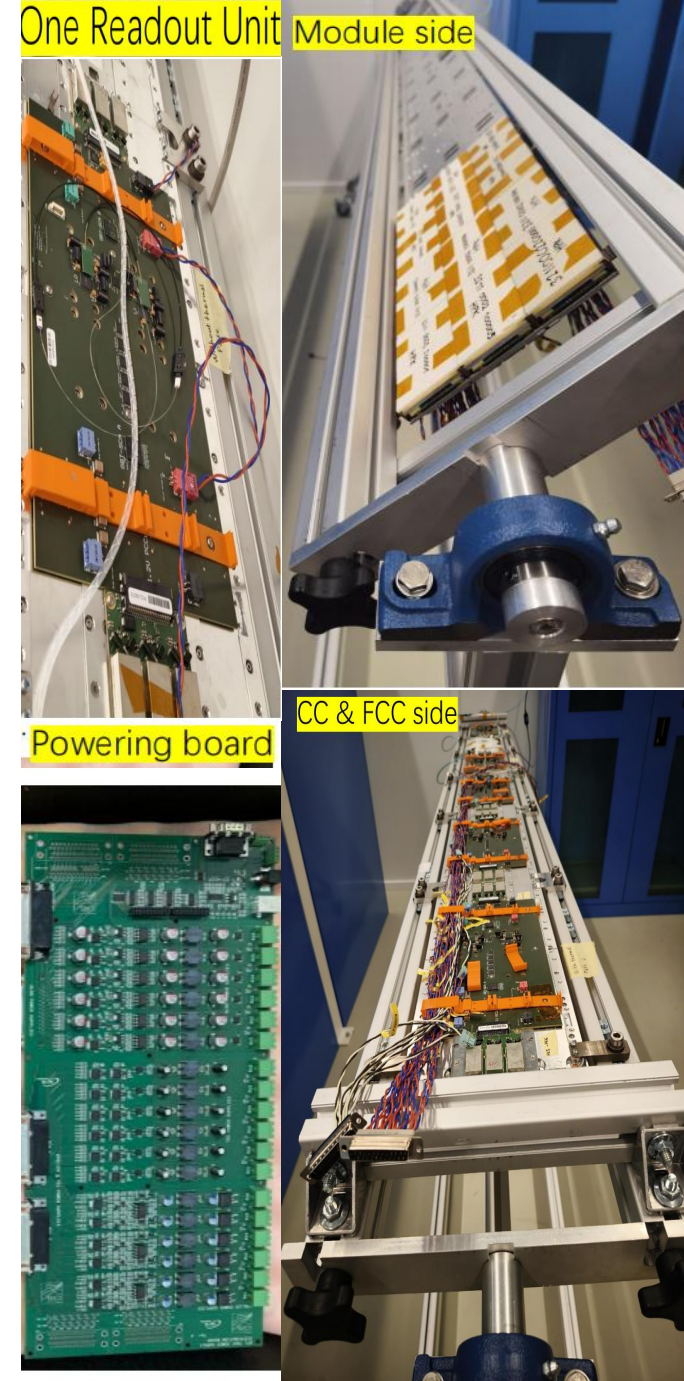


# Tray Thermal Test Setup



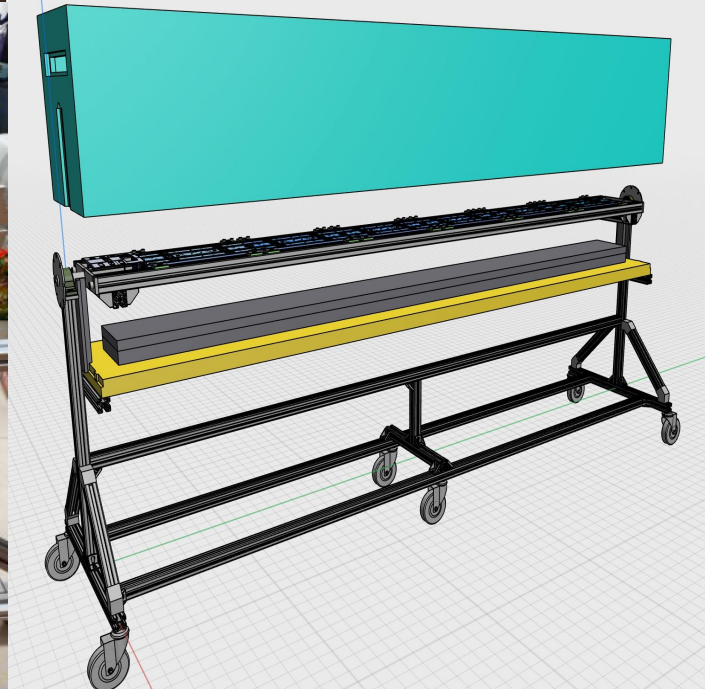
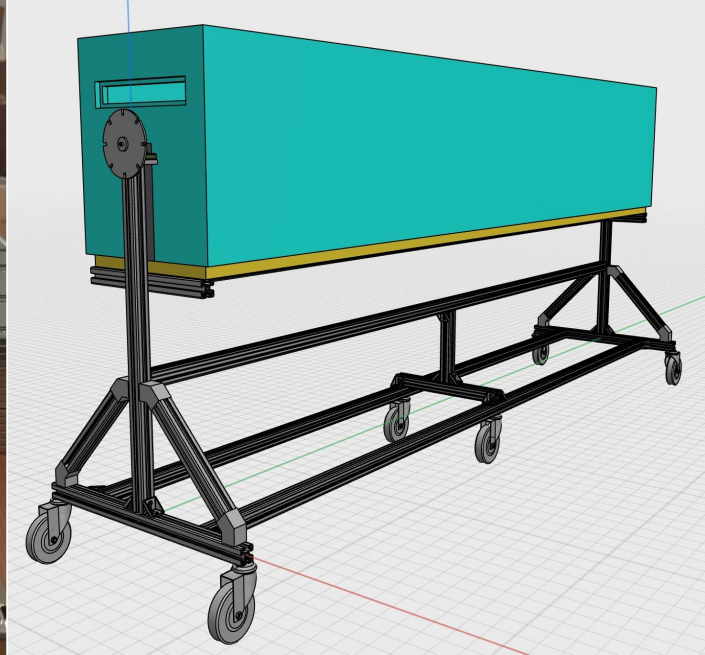
# Introduction of Tray QA/QC Thermal Test

- The tray QA/QC system based on **Serenity board** and custom tray powering board is currently being established
- In March 2024, the first RU was established during the pre-production phase at CERN
- The Tray Thermal test includes **time and temperature acquisition**, with a **constant temperature environment** needed for electronic input/output detection to ensure normal operation.
- The Tray consists of **RU, DM, and SM**, so Tray QA/QC requires **constant temperature control** and **real-time temperature measurement**.
- **Cooling plate** and **CO2 circulation** installed on it ensure the normal operation of the modules and chips.



# Tray QAQC Thermal Test Setup

- $2.5 \times 0.2 \times 0.03\text{m}$  Aluminum plate with 2 **embedded cooling loops**
- **Plate segmented in 6 pieces (RUs)**
- Cooling loops are held in place with laminas that are attached with screws to the cold plate.
- At PKU, we designed a **tray shelf** to carry the tray, and we also plan to mount a **thermal dark box** made of foam on the tray
- We plan to install a **cooling system** in the thermal dark box and use **AHT20** sensors with **TCA9548A** for real-time temperature monitoring



# Summary





## ➤ SM QA/QC:

- To ensure consistent QA/QC result(**light yield**), temperature is controlled and monitored by using AHT20 sensors and TCA9548A in the dark box system, stabilizing the temperature at **23°C**

## ➤ DM QA/QC:

- Temperature measurements with **MAX31865** modules and **Pt1000** sensors ensure good **TEC-copper housing contact** and uniform temperature across four DM areas, indicating quality assembly.

## ➤ Tray QA/QC:

- PKU is planning a Tray QA/QC system with a design blueprint to meet the environmental and testing requirements for Tray thermal tests, including **temperature control and real-time monitoring**.

# Back Up



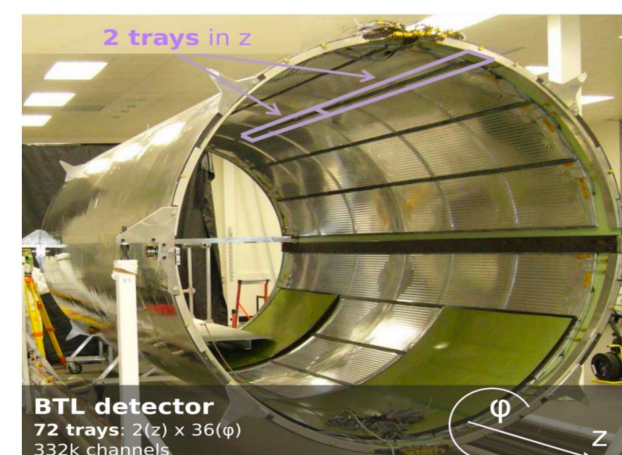
# MTD BTL Overview

## Physics Motivation of MTD

- MTD can effectively suppress pileup, improving the overall accuracy of physical measurements
- MTD provides TOF data, enhancing Higgs precision by **20-30%**, increasing Di-Higgs acceptance by **20%**, reducing SUSY background by **40%**, and **boosting sensitivity to long-lived particles**

## What is MTD BTL ?

- BTL is a single-layer MIP detector located in-between the outer tracker (OT) and the inner wall of the BTL\_x0002\_Tracker Support Tube (BTST)
- It will measure time with  $\sim 30\text{-}60\text{ps}$  resolution.
- Thin ( $< 4\text{cm}$ ), large area ( $38\text{m}^2$ ) detector covering  $|\eta| < 1.5$
- $\sim 10\text{k}$  Sensor Modules, each containing **16** scintillating LYSO crystal bars and two **16-channel** SiPM arrays

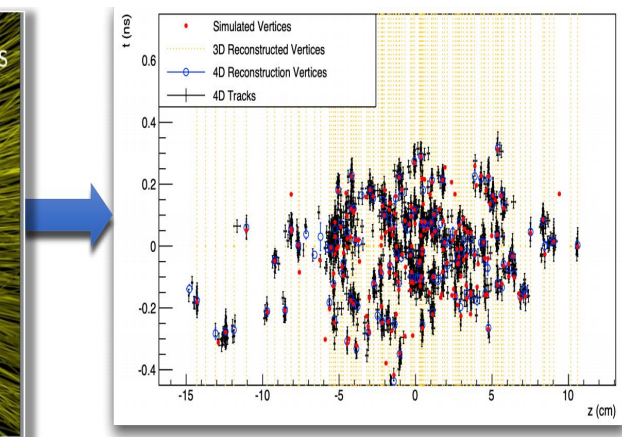
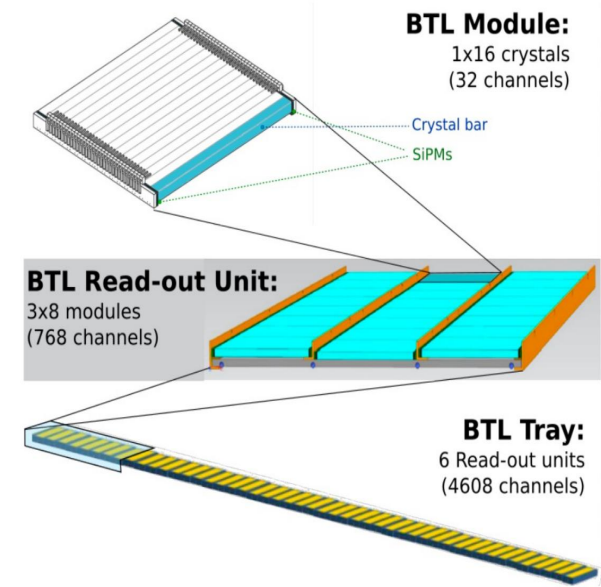
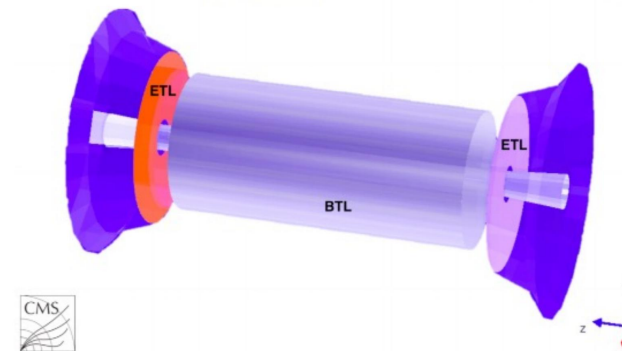


**BTL: LYSO bars + SiPM readout:**

- TK / ECAL interface:  $|\eta| < 1.45$
- Inner radius: 1148 mm (40 mm thick)
- Length:  $\pm 2.6$  m along z
- Surface  $\sim 38\text{m}^2$ ; 332k channels
- Fluence at  $4\text{ab}^{-1}$ :  $2 \times 10^{14}\text{ n}_{\text{p}}/\text{cm}^2$

**ETL: Si with internal gain (LGAD):**

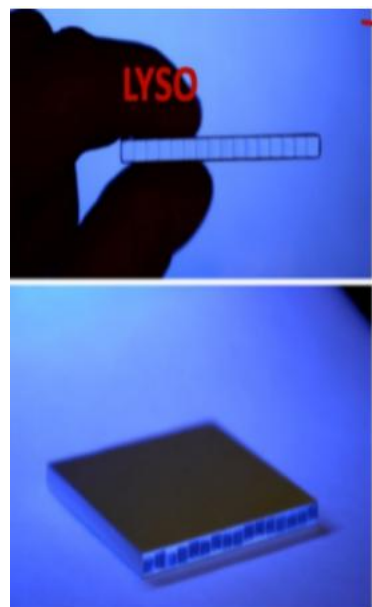
- On the CE nose:  $1.6 < |\eta| < 3.0$
- Radius:  $315 < R < 1200$  mm
- Position in z:  $\pm 3.0$  m (45 mm thick)
- Surface  $\sim 14\text{m}^2$ ;  $\sim 8.5\text{M}$  channels
- Fluence at  $4\text{ab}^{-1}$ : up to  $2 \times 10^{15}\text{ n}_{\text{p}}/\text{cm}^2$



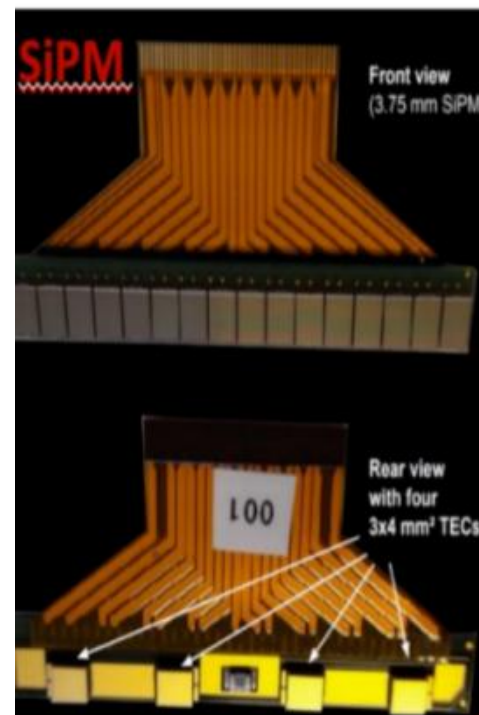
LYSO stands for **Lutetium-Yttrium Oxyorthosilicate**. This is an inorganic scintillator material, formally known as **Lutetium Yttrium Orthosilicate** ( $\text{Lu}_2(\text{SiO}_4)\text{O}$ ).



Radioactive Source



optical signal



electrical signal



The APD (avalanche photodiode)

The MPPC (multi-pixel photon counter)

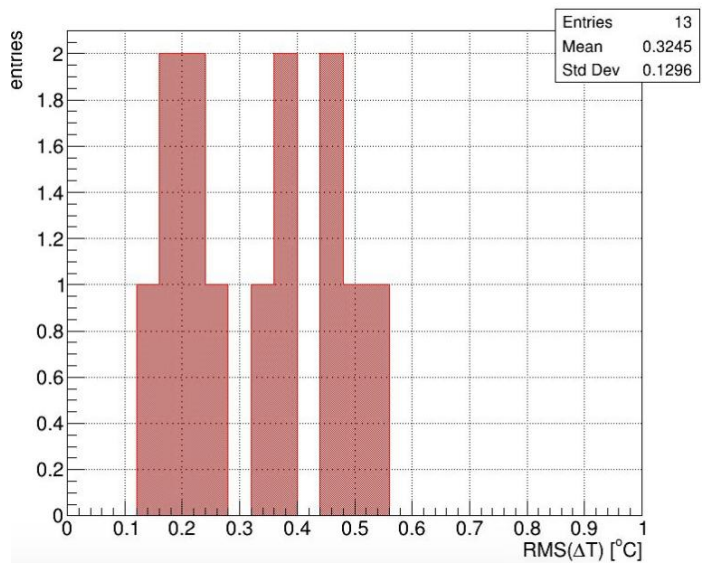
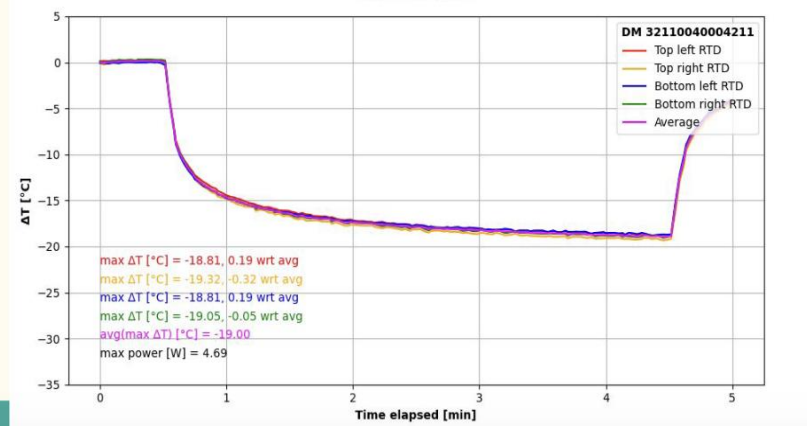
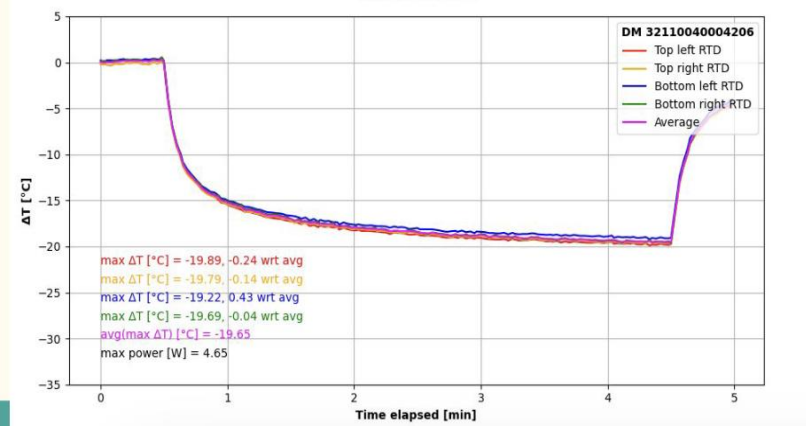
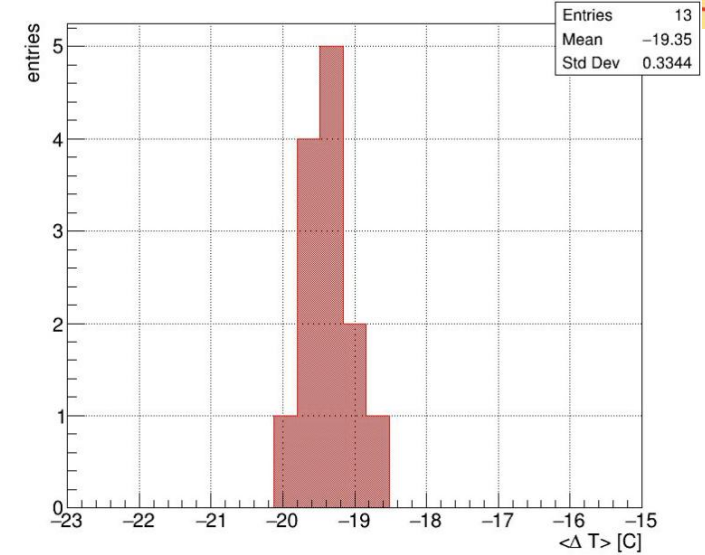
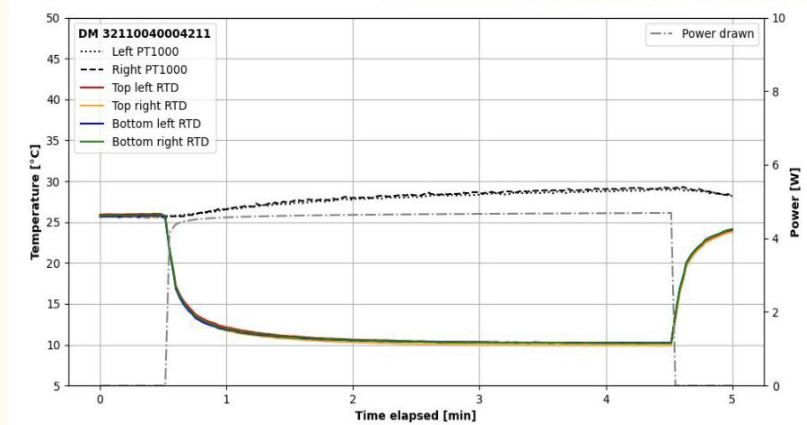
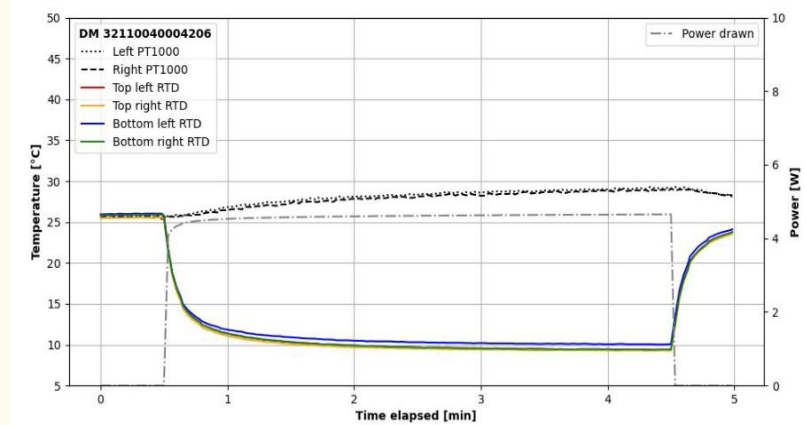
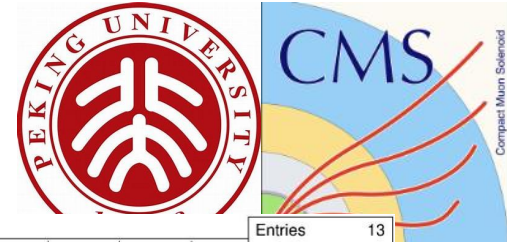
Silicon PhotoMultipliers



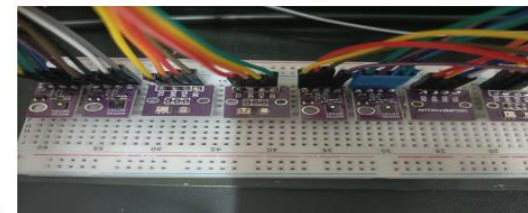
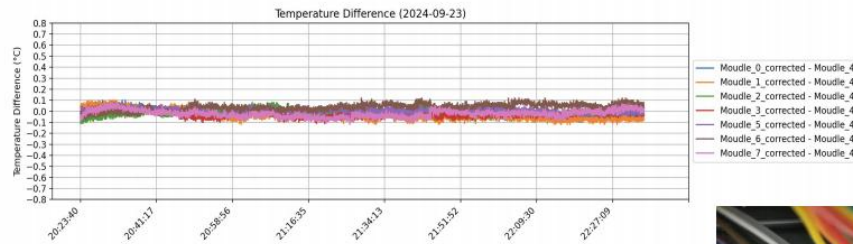
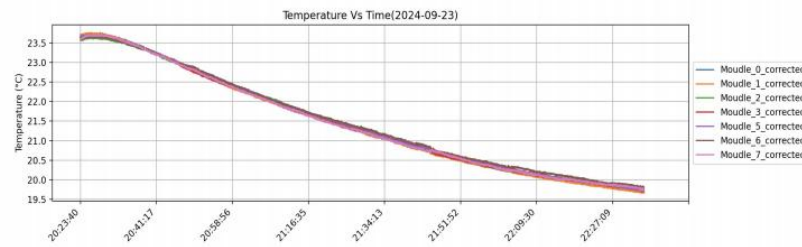
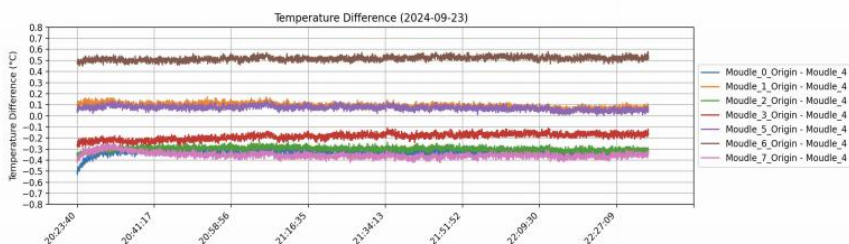
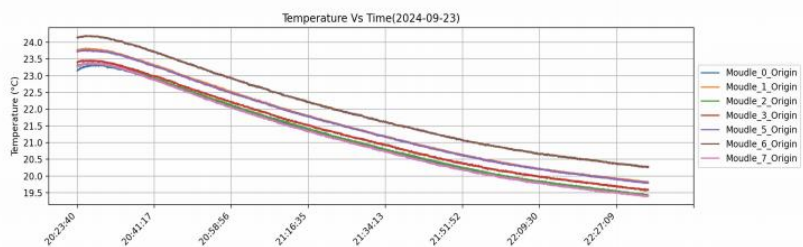
In the MPPC operation just the same as with APD, pulses are produced not only by photon-generated carriers but also by thermally-generated carriers. The pulses produced by the latter are called the dark pulses. The dark pulses are

In a dark state, the number of pixels where avalanche multiplication occurred equals the dark count rate, so the dark current  $I_D$  can be approximated to equation (9) using  $N_{0.5 \text{ p.e.}}$  and  $P_{\text{crosstalk}}$ . If the gain and crosstalk probability at a particular reverse voltage are known, then the dark current can be roughly estimated from the dark count rate and vice versa.

$$I_D \approx q M \boxed{N_{0.5 \text{ p.e.}}} \frac{1}{1 - P_{\text{crosstalk}}} \dots\dots\dots (9)$$



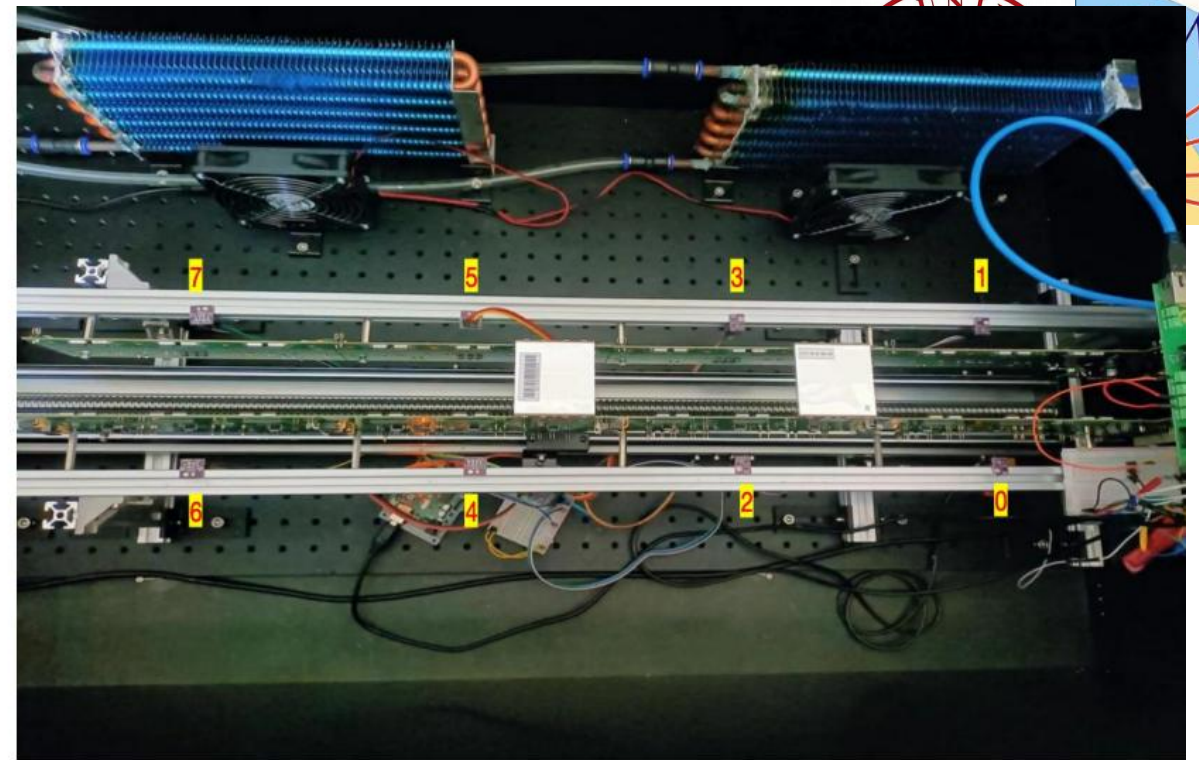
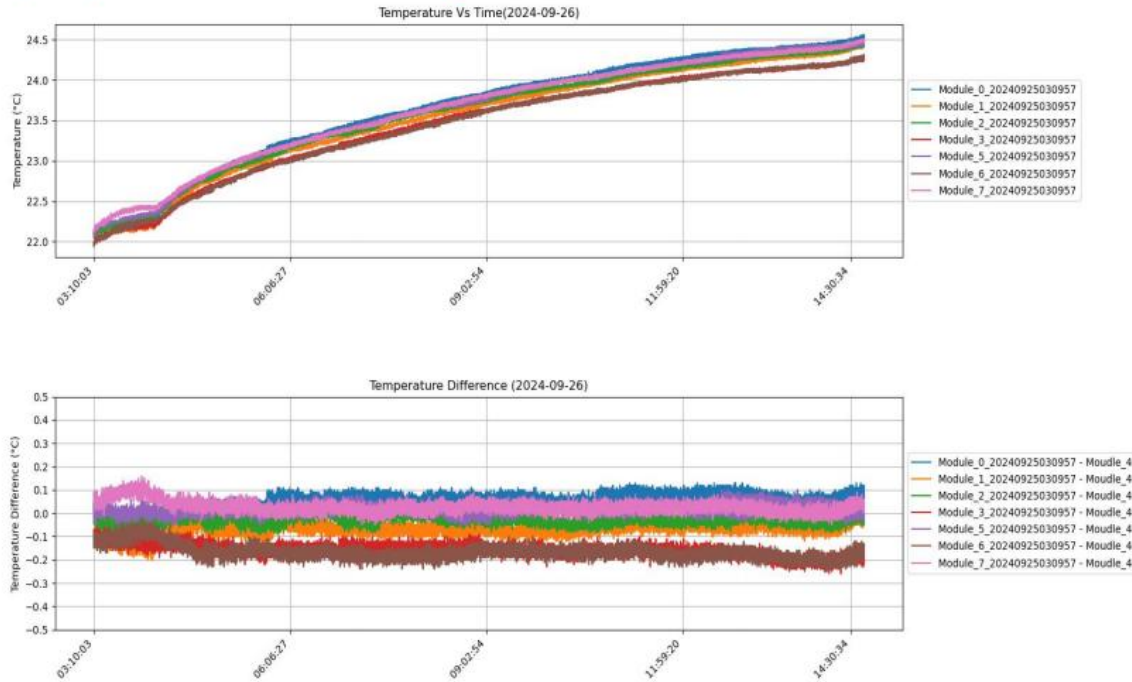
## Temperature Correction



- Firstly, eliminate the temperature measurement **differences between each sensor**
- Place all 8 sensors together to measure temperature, then correct their readings based on “Moudle\_4”, the most accurate sensor.
- **Only the air conditioning is on, without turning on water cooling system and QAQC test system**
- According to this cooling process ( $24^{\circ}\text{C}$  to  $19.5^{\circ}\text{C}$ ), we create **correction JSON files** with the temperature differences between "Moudle\_4" and other sensors at each  $0.1^{\circ}\text{C}$  step
- After correction by **JSON files**, the temperature error is about  $\pm 0.1^{\circ}\text{C}$ , which is within the acceptable range

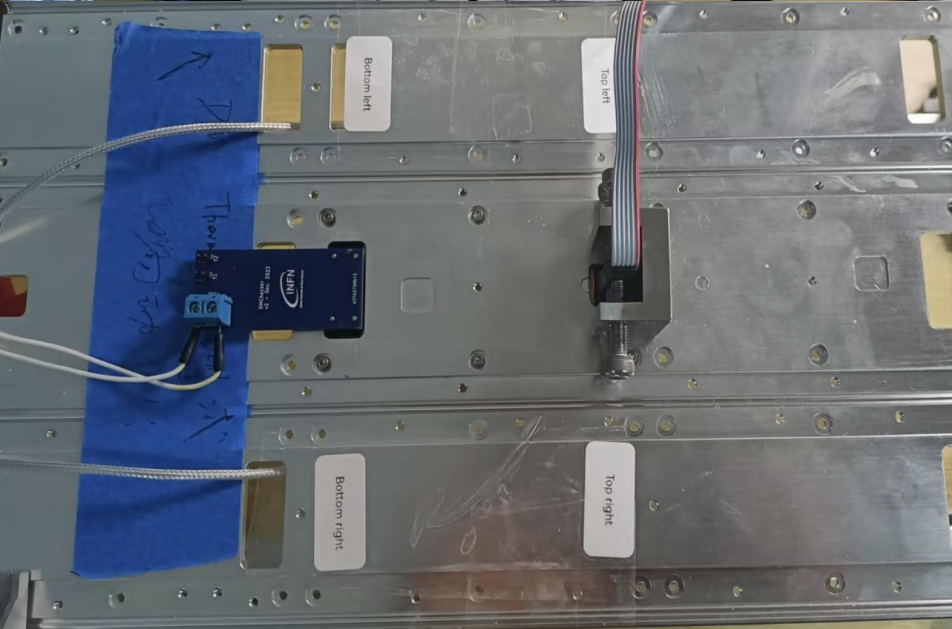
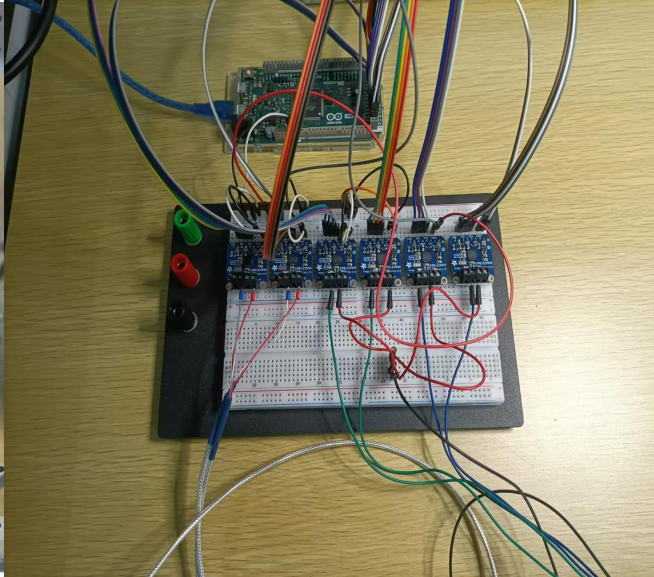
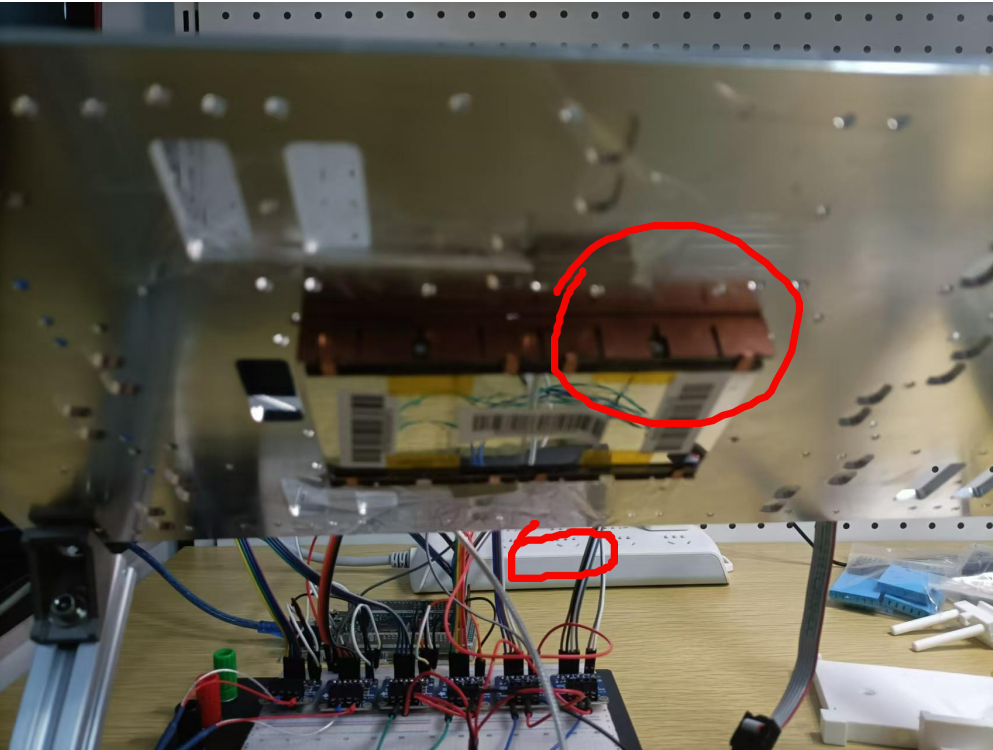


# T(°C) differences at 8 postions After correction



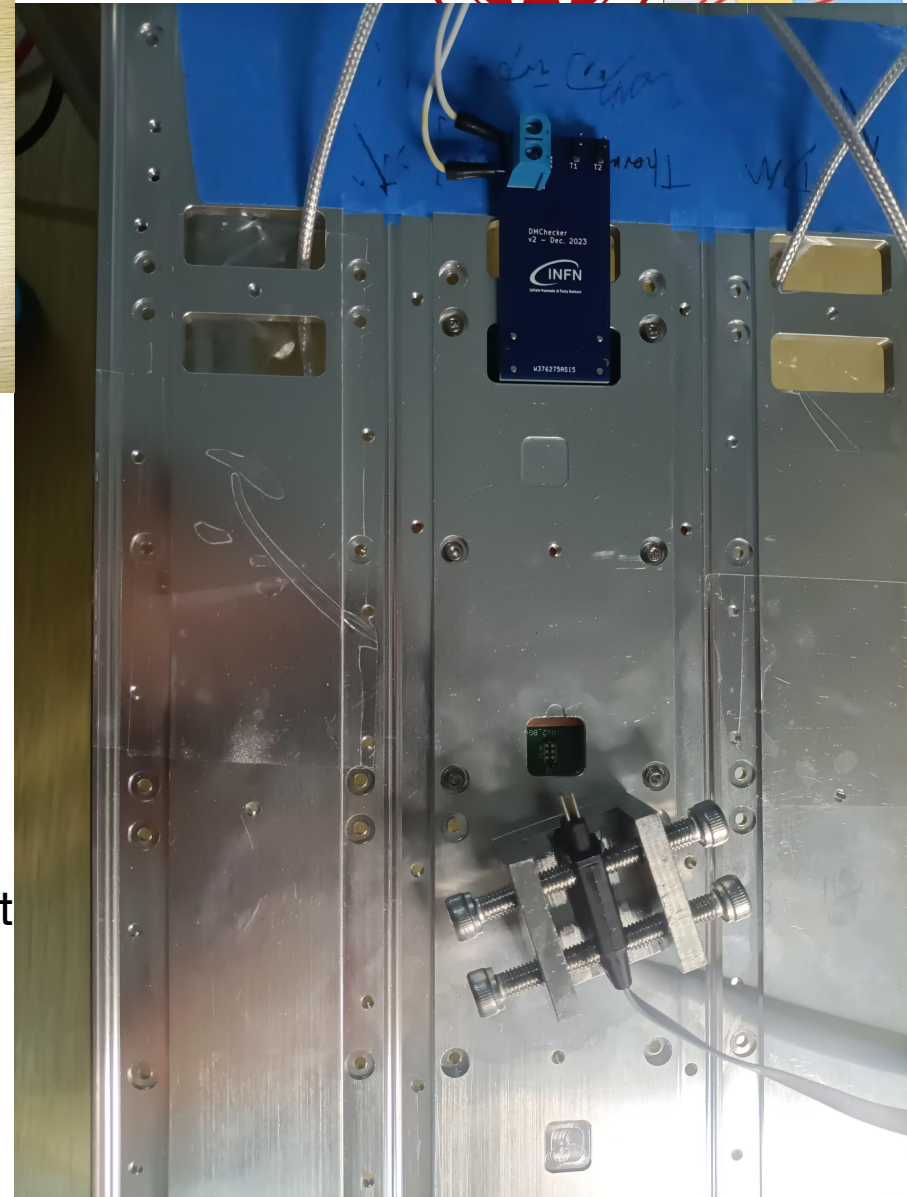
- We sealed the dark box and completed the simple test with only the air conditioning on, without turning on water cooling system and QAQC test system
- After correction, the temperature differences across 8 positions are minimal ( $\pm 0.1^{\circ}\text{C} \sim \pm 0.2^{\circ}\text{C}$ ), indicating uniformity in the dark box.



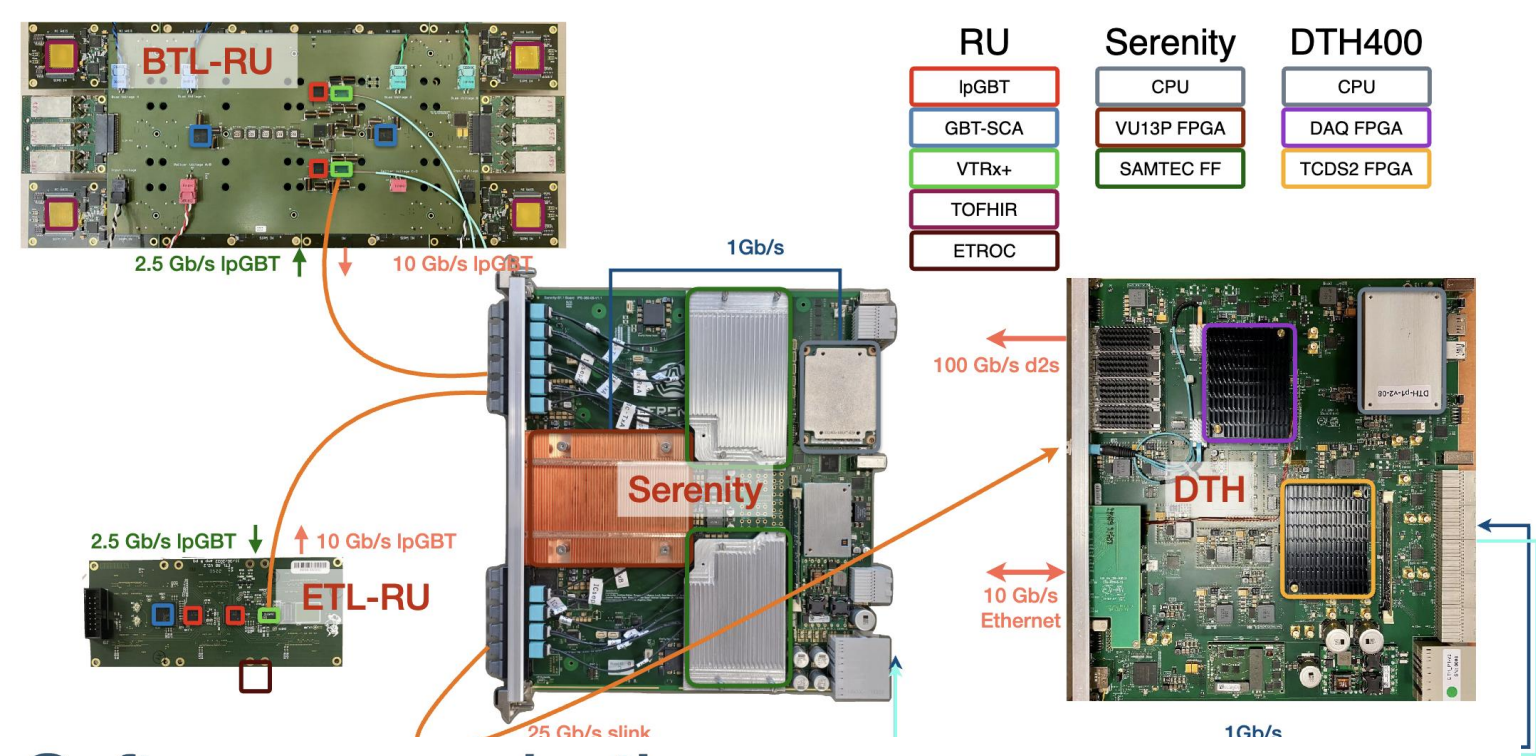


DMchecker:

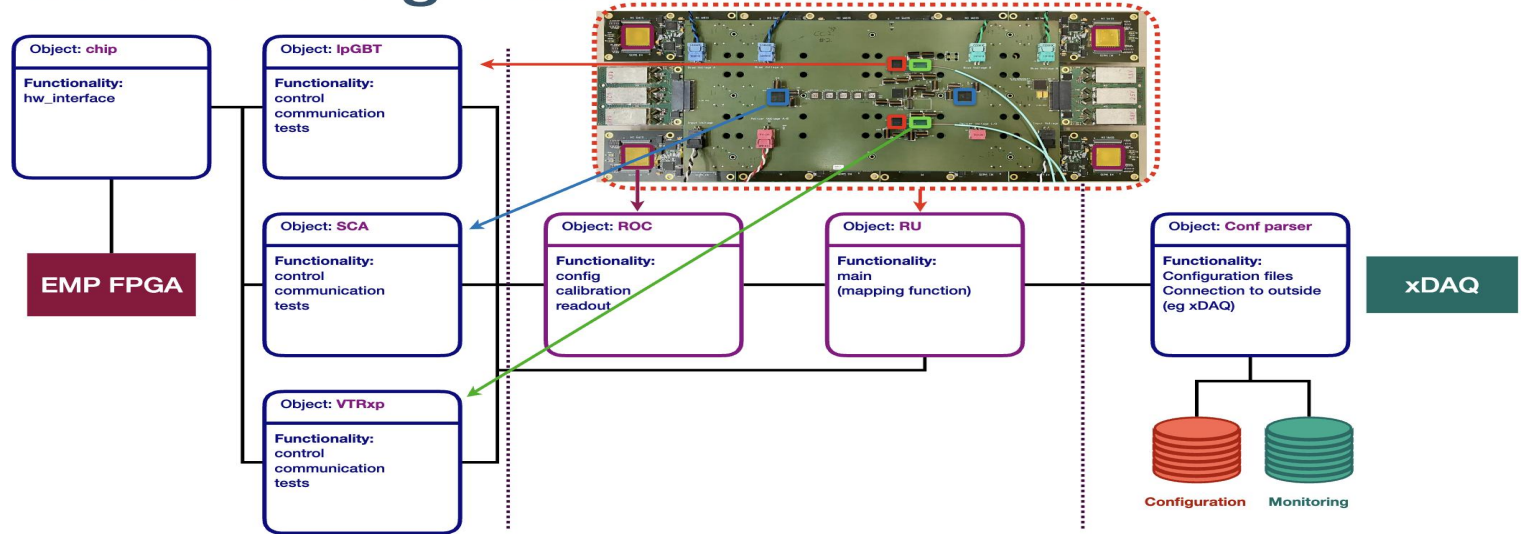
The DM Checker operates by connecting the SiPMs to an external LCR meter, which enables precise measurement of the Detector module's resistance.







# Software organization

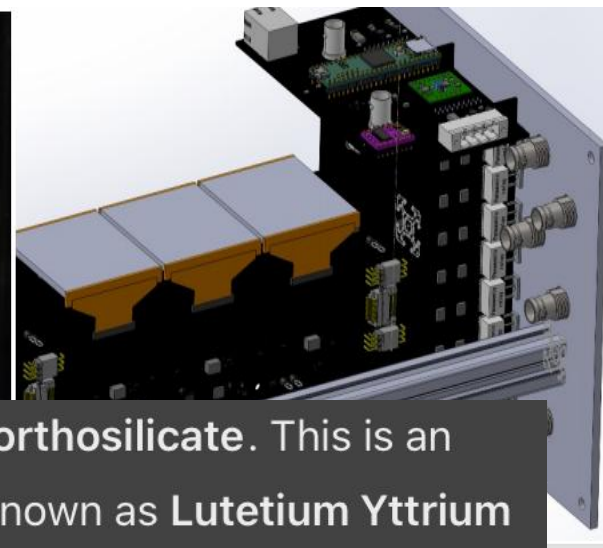


[FMTD\\_DAQ\\_Hackathon.pdf](#)



Heat

Automated movement of radioactive sources



LYSO stands for Lutetium-Yttrium Oxyorthosilicate. This is an inorganic scintillator material, formally known as Lutetium Yttrium Orthosilicate ( $\text{Lu}_2(\text{SiO}_4)\text{O}$ ).

